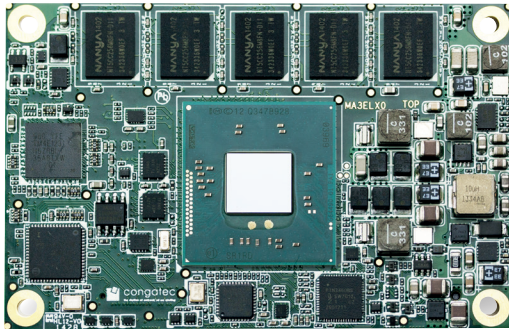


POWERFULL AND SMALL

conga-MA3E

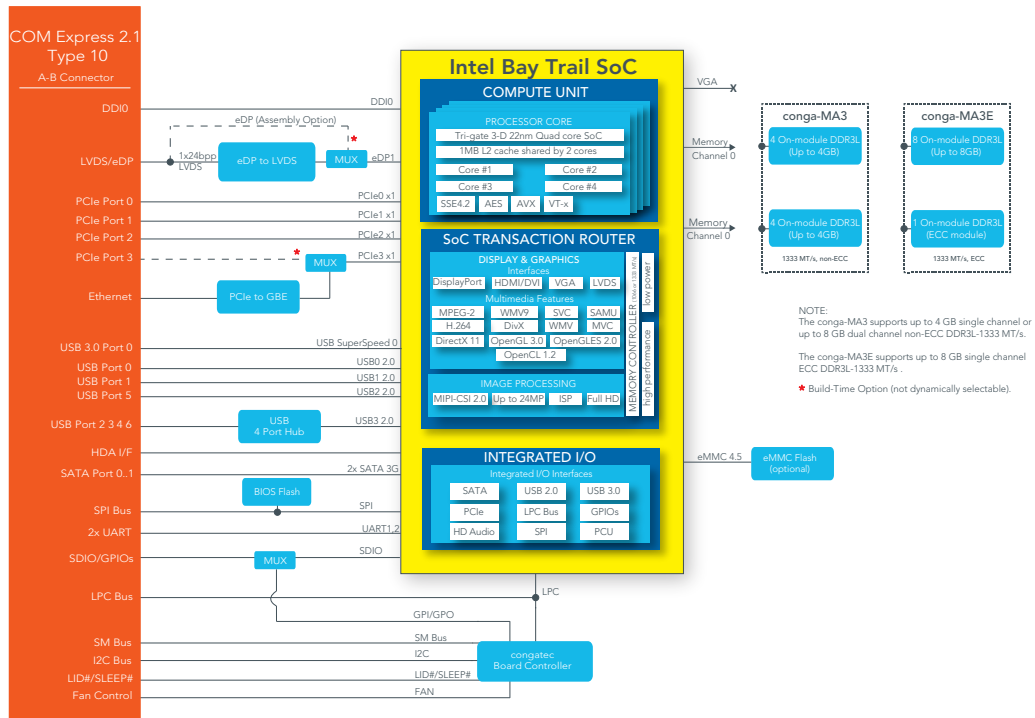


- 3rd Gen. Intel® Atom™ | Intel® Celeron® processor family
- COM Express Mini Type 10 module
- ECC protected memory up to 8 GByte
- High resolution Intel® Gen. 7 graphics
- Temperature range up to -40°C .. +85°C

COM  **Express®**

Formfactor	Formfactor COM Express® Mini (55 x 84 mm) Type 10
CPU	Intel® Atom™ E3845 1.91GHz Quad Core L2 cache 2MB 10W TDP Intel® Atom™ E3827 1.75GHz Dual Core L2 cache 1MB 8W TDP
DRAM	Onboard DDR3L memory support for up to 8 Gbytes of ECC memory up to 1333MT/s
Chipset	Integrated in SoC
Onboard storage	eMMC 4.51 interface up to 64GB of MLC NAND up to 32GB of SLC NAND up to 4GB of SLC NAND
Ethernet	Intel I210 Gigabit Ethernet
I/O Interfaces	Up to 4x PCIe x1 lanes with 5 Gb/s PCI Express 2.0 2x SATA 2.0 3Gb/s ports 7x USB 2.0 1x USB 3.0 LPC SPI I ² C bus (fast mode 400 kHz, multi-master) SDIO
Sound	Digital High Definition Audio Interface
Graphics	Intel® HD Graphics Gen 7 Full hardware acceleration for MPEG2 H.264 DirectX11 OCL 1.2 OGL 3.2 WMV9 and VC1
LVDS	Single channel LVDS transmitter support for flat panels with 1x18 bit/1x24 bit data mapping up to a resolution of 1920x1200@60Hz.
Digital Display Interface	Displayport 1.1 up to 2560x1600 or HDMI 1.4a / DVI up to 1920x1200
congatec Board Controller	Multi Stage Watchdog non-volatile User Data Storage Manufacturing and Board Information Board Statistics BIOS Setup Data Backup I ² C bus (fast mode, 400 kHz, multi-master) Power Loss Control
Embedded BIOS Features	OEM Logo OEM CMOS Defaults LCD Control Display Auto Detection Backlight Control Flash Update based on AMI Aptio UEFI
Power Management	ACPI 5.0 with battery support
Operating Systems	Microsoft® Windows 10 Microsoft® Windows 10 IoT Enterprise Microsoft® Windows 10 IoT Core Microsoft® Windows® 8 Microsoft® Windows® 7 Linux Microsoft® Windows® Embedded Standard Microsoft® Windows® 7 Embedded Compact Android Yocto MoonIsland / WindRiver IDP
Power Consumption	Typ. application: see User's Guide for full details
Temperature	Commercial : Operating: 0 to +60°C Storage: -20 to +80°C Industrial : Operating: -40 to +85°C Storage: -45 to +85°C
Humidity	Operating: 10 - 90% r. H. non cond. Storage: 5 - 95% r. H. non cond.
Size	55 x 84 mm (2.17" x 3.31")

conga-MA3E | Block diagram



conga-MA3E | Order Information

Article	PN	Description
conga-MA3E/E3845-4G eMMC8	048400	Intel® Atom™ E3845 quad core processor with 1.91GHz 2MB L2 cache 4GB 1333MT/s DDR3L onboard ECC memory and 8GB eMMC onboard flash.
conga-MA3E/i-E3845-4G eMMC8	048410	Intel® Atom™ E3845 quad core processor with 1.91GHz 2MB L2 cache 4GB 1333MT/s DDR3L onboard ECC memory and 8GB eMMC onboard flash Industrial grade temperature range from -40°C to 85°C.
conga-MA3E/i-E3827-2G eMMC4	048411	Intel® Atom™ E3827 dual core processor with 1.75GHz 1MB L2 cache 2GB 1333MT/s DDR3L onboard ECC memory and 4GB eMMC onboard flash Industrial grade temperature range from -40°C to 85°C.
conga-MA30/HSP-T	047450	Standard heatspreader for COM Express Type 10 module conga-MA3. All standoffs are M2.5 thread.
conga-MA30/HSP-B	047451	Standard heatspreader for COM Express Type 10 module conga-MA3. All standoffs are 2.7mm bore hole.
conga-MA30/CSP-T	047452	Standard passive cooling solution for COM Express Type 10 module conga-MA3 with fins. All standoffs are M2.5mm thread.
conga-MA30/CSP-B	047453	Standard passive cooling solution for COM Express Type 10 module conga-MA3 with fins. All standoffs are 2.7mm bore hole.

Accessories

conga-MEVAL	065400	Evaluation carrier board for Type 10 COM-Express-modules
conga-LDVI/EPI	011115	LVDS to DVI converter board for digital flat panels with onboard EEPROM
COM-Express-carrier-board-Socket-5	400007	Connector for COM-Express carrier boards height 5mm packing unit 4 pieces
COM-Express-carrier-board-Socket-8	400004	Connector for COM-Express carrier boards height 8mm packing unit 4 pieces